

Title (en)
Thermally conductive grease composition

Title (de)
Wärmeleitende Schmierfettzusammensetzung

Title (fr)
Composition thermiquement conductrice de graisse

Publication
EP 0939115 A1 19990901 (EN)

Application
EP 98308489 A 19981016

Priority
• JP 6458198 A 19980227
• JP 6458298 A 19980227

Abstract (en)
A thermally conductive grease composition comprising (A) 100 weight parts of at least one base oil selected from liquid silicones, liquid hydrocarbons or fluorohydrocarbon oils and 500-1,000 weight parts of a thermally conductive filler mixture which is constituted of (B) an inorganic filler having Mohs' hardness of at least 6 and thermal conductivity of at least 100 W/m DEG K and (C) an inorganic filler having Mohs' hardness of at most 5 and thermal conductivity of at least 20 W/m DEG K, and in which the ratio of Component (C) to the sum total of Component (B) and Component (C) is from 0.05 to 0.5 by weight. <IMAGE>

IPC 1-7
C10M 169/02; C08K 3/00; H01L 23/373

IPC 8 full level
C10M 169/04 (2006.01)

CPC (source: EP)
C10M 169/04 (2013.01); **C10M 2201/00** (2013.01); **C10M 2201/041** (2013.01); **C10M 2201/061** (2013.01); **C10M 2201/16** (2013.01); **C10M 2201/18** (2013.01); **C10M 2203/06** (2013.01); **C10M 2205/026** (2013.01); **C10M 2205/028** (2013.01); **C10M 2207/281** (2013.01); **C10M 2207/282** (2013.01); **C10M 2207/283** (2013.01); **C10M 2207/286** (2013.01); **C10M 2207/34** (2013.01); **C10M 2209/104** (2013.01); **C10M 2209/105** (2013.01); **C10M 2209/107** (2013.01); **C10M 2211/06** (2013.01); **C10M 2213/00** (2013.01); **C10M 2213/02** (2013.01); **C10M 2213/04** (2013.01); **C10M 2213/06** (2013.01); **C10M 2213/062** (2013.01); **C10M 2223/04** (2013.01); **C10M 2223/041** (2013.01); **C10M 2223/042** (2013.01); **C10M 2229/041** (2013.01); **C10M 2229/042** (2013.01); **C10M 2229/051** (2013.01); **C10N 2010/04** (2013.01); **H01L 2924/0002** (2013.01)

Citation (search report)
• [X] EP 0823451 A1 19980211 - SHINETSU CHEMICAL CO [JP]
• [A] US 4762174 A 19880809 - ARTUS RAYMONDE G C [GB]
• [XD] EP 0382188 A1 19900816 - DOW CORNING [US]
• [AD] US 5100568 A 19920331 - TAKAHASHI TAKAYUKI [JP], et al
• [A] DATABASE WPI Section Ch Week 8714, Derwent World Patents Index; Class A26, AN 87-096686, XP002104988

Cited by
CN112194899A; CN114106787A; RU2672247C2; CN111433312A; US11236259B2; EP0982391A1; US6136758A; US7135232B2; CN100402626C; CN100376655C; EP0982392A1; US8383005B2; US6372337B2; US10704008B2; US11124727B2; US9969919B2; US10202529B2; US8313243B2; US10023741B2; US9777205B2; WO2013155078A1; US11041072B2; US8618211B2; US11214651B2; US11591470B2; US7695817B2; US9481851B2; US9698077B2; US11319412B2

Designated contracting state (EPC)
DE FR GB

DOCDB simple family (publication)
EP 0939115 A1 19990901

DOCDB simple family (application)
EP 98308489 A 19981016